L Number	Hits	Search Text	DB	Time stamp
-	215	yuji.in. and kamikawa.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:02
-	166	(yuji.in. and kamikawa.in.) and (wafer or semiconductor or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 09:48
-	65	((yuji.in. and kamikawa.in.) and (wafer or semiconductor or substrate)) and rota$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 10:24
-	3638	134/57R,63,66,153,158,161,902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 13:21
-	1884	134/57R,63,66,153,158,161,902.ccls. and (substrate or wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 13:21
-	1307	(134/57R,63,66,153,158,161,902.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/19 10:26
-	635	((134/57R,63,66,153,158,161,902.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)) and (rotary or rotat$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:05
-	345	(((134/57R,63,66,153,158,161,902.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)) and (rotary or rotat$5)) and (vertical$2 and horizontal$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:07
-	128	((((134/57R,63,66,153,158,161,902.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)) and (rotary or rotat$5)) and (vertical$2 and horizontal$2)) and ((transfer or robot$2) with arm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 13:24
-	323	((118/52,53.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)) and (rotary or rotat$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:09
-	172	(((118/52,53.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)) and (rotary or rotat$5)) and (vertical$2 and horizontal$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:08
-	78	((((118/52,53.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)) and (rotary or rotat$5)) and (vertical$2 and horizontal$2)) and ((transfer or robot$2) with arm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:40

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-	3638	134/57R,63,66,153,158,161,902.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 13:21
-	112	134/57R,63,66,153,158,161,902.ccls. and (substrate or wafer or semiconductor) and rotor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:03
-	35	(134/57R,63,66,153,158,161,902.ccls. and (substrate or wafer or semiconductor) and rotor) and ((transfer or robot$2) with arm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:02
-	1620	(tokyo and electron and limited).as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:02
-	568	((tokyo and electron and limited).as.) and ((transfer or robot$2) with arm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:02
-	10	(((tokyo and electron and limited).as.) and ((transfer or robot$2) with arm)) and (substrate or wafer or semiconductor) and rotor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:03
-	1960	118/500,501.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:09
-	343	((118/500,501.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)) and (rotary or rotat$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:11
-	24	(((118/500,501.ccls. and (substrate or wafer or semiconductor)) and (chamber or tank or vessel)) and (rotary or rotat$5)) and rotor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 14:11

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